

AMENDMENTS TO THE CLAIMS

1. (Withdrawn) An information recording medium comprising:  
a substrate produced by injection molding;  
a dye recording layer disposed on said substrate for recording information therein;  
said substrate being selected from two substrates which are simultaneously injection-molded, alternately arranged, and then cooled.

2. (Currently Amended) A method of manufacturing an information recording medium having a substrate produced by injection molding, and a dye recording layer disposed on said substrate for recording information therein, comprising:  
simultaneously injection-molding two substrates;  
alternately arranging said two substrates on one feed mechanism; and  
cooling said two substrates on said feed mechanism.

3. (Original) A method according to claim 2, wherein said information recording medium is manufactured by a manufacturing line comprising:  
a single injection molding apparatus for simultaneously injection-molding said two substrates; and  
four dye solution coating machines,  
wherein each of said dye solution coating machine forms said dye recording layer.

4. (Original) A method according to claim 3, further comprising the step of:  
supporting the injection molded substrates with surfaces thereof oriented substantially vertically on a feed screw mechanism.

5. (Original) A method according to claim 3, further comprising the step of:  
supporting the injection molded substrates flatwise on a rotary table.

6. (Original) A method according to claim 3, further comprising the step of:  
supporting the injection molded substrates with surfaces thereof oriented substantially  
vertically in a rotatable cylinder.

7. (Original) A method according to claim 3, further comprising the step of:  
supporting the injection molded substrates on a rotatable polygonal prism with outer  
facets thereof attracting the substrates, respectively.

**8-10. (Canceled)**

B 11. (Previously Presented) A method according to claim 2, wherein said alternately  
arranging comprises alternately arranging said two substrates at a pitch which is at least 6 times  
the thickness of each of the substrates.

12. (Previously Presented) A method according to claim 11, wherein said alternately  
arranging comprises alternately arranging said two substrates at a pitch which is at most 100  
times the thickness of each of the substrates.

13. (Previously Presented) A method according to claim 2, wherein said alternately  
arranging comprises alternately arranging said two substrates at a pitch which is at least 8 times  
the thickness of each of the substrates.

14. (Previously Presented) A method according to claim 13, wherein said alternately  
arranging comprises alternately arranging said two substrates at a pitch which is at most 30 times  
the thickness of each of the substrates.

15. (Previously Presented) A method according to claim 2, wherein said cooling  
comprises intermittently feeding said two substrates by said feed mechanism at an interval  
ranging from 1 second to 60 seconds.

16. (Previously Presented) A method according to claim 2, wherein said cooling comprises cooling each of said substrates for a period of time which is at least 3 minutes.

17. (Previously Presented) A method according to claim 2, wherein said alternately arranging is performed after a temperature of said substrates is at most 115°C.

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